

Product / Package Information

Package	PSOP_2
Body Size	300 mil
LeadCount	20
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A and B Compliant

Materials Declaration

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic material:	Silica	60678-86-0	2.56 E-01	87.7	877000	63.68		636757
Thermosets	Epoxy Resin	Proprietary	1.46 E-02	5.0	50000	3.63		36303
Thermosets	Phenol Resin	Proprietary	1.46 E-02	5.0	50000	3.63		36303
Thermosets	Epoxy Cresol Novolac	29690-82-2	5.84 E-03	2.0	20000	1.45		14521
Other inorganic material:	Carbon Black	1333-86-3	8.76 E-04	0.3	3000	0.22		2178
Subtotal			2.92 E-01	100	1000000	72.61		726063

Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	9.81 E-02	97.57	975706	24.40		243987
Copper & its alloys	Iron	7439-89-6	2.29 E-03	2.28	22789	0.57		5699
Copper & its alloys	Zinc	7440-66-6	1.27 E-04	0.13	1263	0.03		316
Copper & its alloys	Phosphorus	7723-14-0	2.44 E-05	0.02	242	0.01		61
Subtotal			1.01 E-01	100.00	1000000	25.01		250062

Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.23 E-03	100.0	1000000	0.31		3068

External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	3.70 E-03	100.0	1000000	0.92		9187

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.04 E-03	99.99	1000000	0.26		2586

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic material:	Doped Silicon	7440-21-3	2.77 E-03	100.0	1000000	0.69		6892

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	6.33 E-04	73.40	734000	0.16		1573
Thermoset	Epoxy Resin	Proprietary	1.58 E-04	18.35	183500	0.04		393
Other inorganic material:	Metal oxide	Proprietary	2.37 E-05	2.75	27500	0.01		59
Others	Curing and hardening agen	Proprietary	2.37 E-05	2.75	27500	0.01		59
Other organic material:	Gamma Butyrolactone	96-48-0	2.37 E-05	2.75	27500	0.01		59
Subtotal			8.62 E-04	100.00	1000000	0.21		2143

				Weight (g)	Percentage (%)		PPM
Package Totals				4.02 E-01	100.00		1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge;
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
 any inaccuracy of such information



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